

CLAIM AMENDMENTS

1. (Currently Amended) A chemical processor comprising:
a chemical processing cup, in which a member-to-be-processed is to be provided placed; and
a pumping device for circulating a liquid chemical within said chemical processing cup, wherein said the member-to-be-processed has a surface-to-be-processed which is placed face up in said chemical processing cup, said surface-to-be-processed is chemically processed while said the liquid chemical is circulated along said the surface-to-be-processed in substantially a given single direction at all times and at a velocity gradient of at least 300/second ~~or more~~.
2. (Currently Amended) The chemical processor according to claim 1, wherein said chemical processing cup has includes a chemical inlet port and a chemical drain port, and including a regulation member capable of regulating ~~an~~ effective aperture area is provided located at said chemical drain port.
3. (Currently Amended) The chemical processor according to claim 1, wherein including a flow rate regulation plate opposing said the surface-to-be-processed is provided and located in said chemical processing cup.
4. (Currently Amended) A chemical processing method comprising ~~the steps of~~:
placing a member-to-be-processed having a plurality of blind holes formed in a surface-to-be-processed in a chemical processing cup such that with said surface-to-be-processed ~~is~~ oriented upward; and
chemically processing said surface-to-be-processed while by circulating a liquid chemical ~~is circulated~~ along said surface-to-be-processed in substantially a given single direction at all times and at a velocity gradient of at least 300/second ~~or more~~.
5. (Currently Amended) The method of processing a chemical according to claim 4, wherein said member-to-be-processed is a semiconductor wafer, and including cleaning the insides of said blind holes ~~are cleansed~~ with said liquid chemical.
6. (Currently Amended) The method of processing a chemical according to claim 4, wherein said member-to-be-processed is a semiconductor wafer, and including plating said blind holes ~~are plated with~~ using said liquid chemical.

7. (Currently Amended) The method of processing a chemical according to claim 4, wherein ~~an~~ aspect ratio of said blind ~~hole~~ holes is no more than 2 or less.

8. (Currently Amended) A method for manufacturing a semiconductor device comprising ~~the steps of:~~

placing a semiconductor wafer having a plurality of blind holes ~~formed~~ in a surface-to-be-processed in a chemical processing cup ~~such that~~ with said surface-to-be-processed is oriented upward;

chemically processing said surface-to-be-processed ~~while by circulating~~ a liquid chemical ~~is circulated~~ along said surface-to-be-processed in substantially a ~~given~~ single direction at all times and at a velocity gradient of at least 300/second ~~or more~~.

9. (Currently Amended) The method for manufacturing a semiconductor device according to claim 8, ~~wherein~~ including cleaning the insides of said blind holes ~~is cleansed~~ while said semiconductor wafer is chemically processed.

10. (Currently Amended) The method for manufacturing a semiconductor device according to claim 8, ~~wherein~~ including plating said blind holes ~~are plated~~ while said semiconductor wafer is chemically processed.

11. (Currently Amended) The method of manufacturing a semiconductor device according to claim 8, wherein ~~an~~ aspect ratio of said blind ~~hole~~ holes is no more than 2 or less.